

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Ying Sing Fung	09/10/2008
Sun Hui	09/10/2008
Mo Zhihong	09/10/2008
Zhu Derong	09/10/2008
Jacqueline T.S. Choy	09/10/2008
Yin Yee Lee	09/10/2008
<b>RECEIVING PARTY DATA</b>	
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City:	Hong Kong
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
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Total Attachments: 2

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## ASSIGNMENT

WHEREAS, We, **FUNG Ying Sing, SUN Hui, MO Zhihong, ZHU Derong, CHOY Tsz Shan, Jacqueline and LEE Yin Yee** ASSIGNORS, citizens of Hong Kong SAR, China, China, Hong Kong SAR, Hong Kong SAR and Hong Kong SAR, residing at Flat G, 9th Floor, Fenton Court, Tower 27 South Horizons Phase 4, 27 Yi Nam Road, Ap Lei Chau, Hong Kong, 14F-Flat 7, Hang Sing Mansion, 48-78 High Street, Hong Kong, 5th Floor, No. 2, High Street, Hong Kong, Ground Floor, No. 5, Hinhan Road, Hong Kong, Flat D, 35th Floor, Block 6, Saddle Ridge Garden, Ma On Shan, New Territories, Hong Kong and 18C, Tower 1, Sham Wan Tower, 3 Ap Lei Chau Drive, Ap Lei Chau, Hong Kong are the inventors of the invention in **Electronic Tongue Sensor** for which we have executed an application for a Patent of the United States

which is identified by Berkeley Law and Technology Group, LLP docket no. 063.P002 which was filed on **10 September 2008**, Application No. **12/208,262**.

and WHEREAS, The University of Hong Kong, ASSIGNEE, located at Pokfulam Road, HONG KONG is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, WE, the said ASSIGNORS, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, our entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewal and reissues thereof;

AND WE HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testifying in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, We hereunto set our hands and seals the day and year set opposite our respective signatures.

Date Sept 16, 2008, 2008

Witness:

Wu Ruige  
Printed Name

Y S Fung L.S.  
FUNG Ying Sing

Wu Ruige  
Signature

Date Sep. 10, 2008

Witness:

DU FUYANG  
Printed Name

Sun Hui L.S.  
SUN Hui

Du Fuyang  
Signature

Date Sep. 10, 2008

Witness:

DU FUYANG  
Printed Name

莫志红 L.S.  
MO Zhihong

Du Fuyang  
Signature

Date Sep. 10, 2008

Witness:

SZE KWAN LOK  
Printed Name

Zhu Derong L.S.  
ZHU Derong

Zhu Derong  
Signature

Date Sep. 10, 2008

Witness:

ZHAO WEN FENG  
Printed Name

T.S. Choy L.S.  
CHOY Tsz Shan, Jacqueline

Zhao Wenfeng  
Signature

Date Sep. 10, 2008

Witness:

NIE ZHOU  
Printed Name

LEE Yiu Yee L.S.  
LEE Yiu Yee

Nie Zhou  
Signature